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U.S.S.N. 10/002,544

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chung-Shi Liu et al.

Group Art Unit: 1742

Serial No.: 10/002,544

Examiner: W.T. Leader

Filed: 11/21/2001

In Response to Office Action
Dated: 10/09/2003

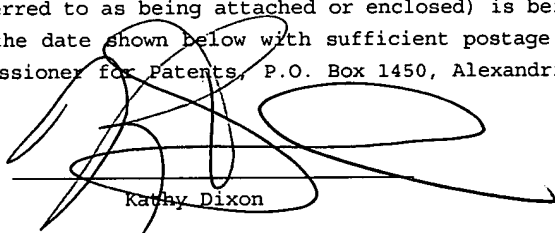
For: A METHOD FOR FORMING CATHODE CONTACT AREAS FOR AN
ELECTROPLATING PROCESS

Attorney Docket No.: 67,200-535

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Va 22313-1450

Date: Jan. 8, 2004


Kathy Dixon

RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, Va 22313-1450

Dear Sir:

In response to an Office Action mailed 10/09/2003,
please enter the following amendments and consider the following
remarks. The Commissioner is hereby authorized to charge Deposit
Account No. 50-0484 any fee due as a result of this amendment.